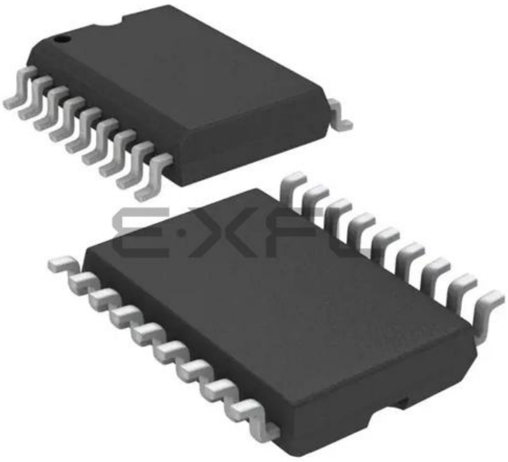

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc717t-e-so

TABLE 1-1: PIC16C717/770/771 PINOUT DESCRIPTION

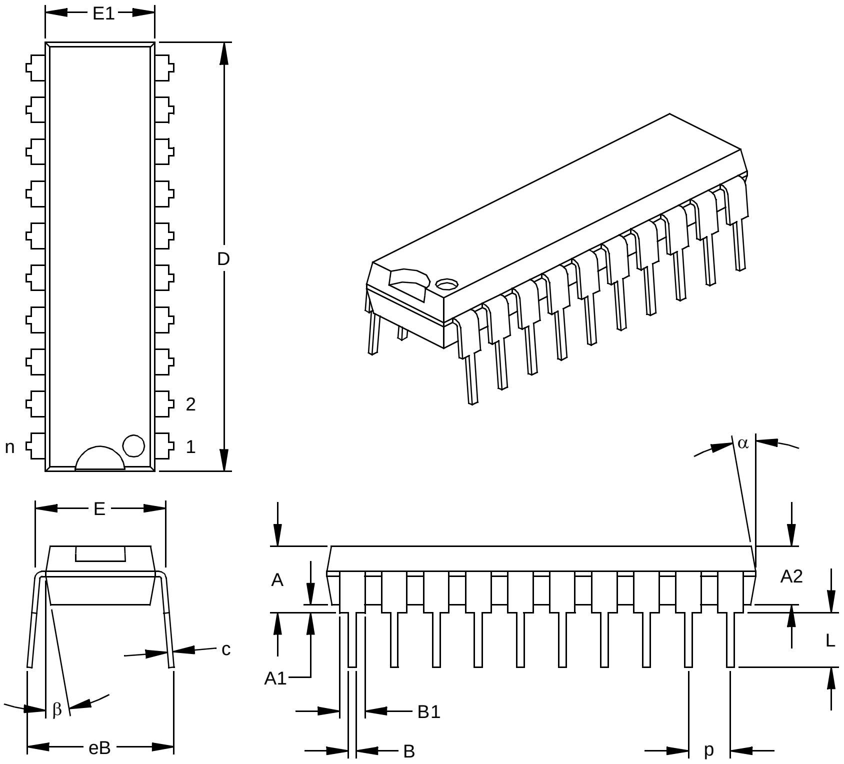
Name	Function	Input Type	Output Type	Description
RA0/AN0	RA0	ST	CMOS	Bi-directional I/O
	AN0	AN		A/D input
RA1/AN1/LVDIN	RA1	ST	CMOS	Bi-directional I/O
	AN1	AN		A/D input
	LVDIN	AN		LVD input reference
RA2/AN2/VREF-/VRL	RA2	ST	CMOS	Bi-directional I/O
	AN2	AN		A/D input
	VREF-	AN		Negative analog reference input
	VRL		AN	Internal voltage reference low output
RA3/AN3/VREF+/VRH	RA3	ST	CMOS	Bi-directional I/O
	AN3	AN		A/D input
	VREF+	AN		Positive analog reference input
	VRH		AN	Internal voltage reference high output
RA4/T0CKI	RA4	ST	OD	Bi-directional I/O
	T0CKI	ST		TMR0 clock input
RA5/$\overline{\text{MCLR}}$/VPP	RA5	ST		Input port
	$\overline{\text{MCLR}}$	ST		Master clear
	VPP	Power		Programming voltage
RA6/OSC2/CLKOUT	RA6	ST	CMOS	Bi-directional I/O
	OSC2		XTAL	Crystal/resonator
	CLKOUT		CMOS	FOSC/4 output
RA7/OSC1/CLKIN	RA7	ST	CMOS	Bi-directional I/O
	OSC1	XTAL		Crystal/resonator
	CLKIN	ST		External clock input/ER resistor connection
RB0/AN4/INT	RB0	TTL	CMOS	Bi-directional I/O(1)
	AN4	AN		A/D input
	INT	ST		Interrupt input
RB1/AN5/$\overline{\text{SS}}$	RB1	TTL	CMOS	Bi-directional I/O(1)
	AN5	AN		A/D input
	$\overline{\text{SS}}$	ST		SSP slave select input
RB2/SCK/SCL	RB2	TTL	CMOS	Bi-directional I/O(1)
	SCK	ST	CMOS	Serial clock I/O for SPI
	SCL	ST	OD	Serial clock I/O for I^2C
RB3/CCP1/P1A	RB3	TTL	CMOS	Bi-directional I/O(1)
	CCP1	ST	CMOS	Capture 1 input/Compare 1 output
	P1A		CMOS	PWM P1A output
RB4/SDI/SDA	RB4	TTL	CMOS	Bi-directional I/O(1)
	SDI	ST		Serial data in for SPI
	SDA	ST	OD	Serial data I/O for I^2C
RB5/SDO/P1B	RB5	TTL	CMOS	Bi-directional I/O(1)
	SDO		CMOS	Serial data out for SPI
	P1B		CMOS	PWM P1B output

Note 1: Bit programmable pull-ups.

2: Only in PIC16C770/771 devices.

17.5 20-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



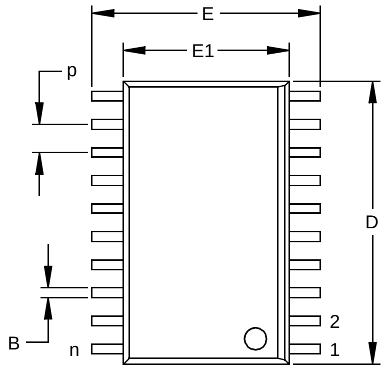
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.295	.310	.325	7.49	7.87	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	1.025	1.033	1.040	26.04	26.24	26.42
Tip to Seating Plane	L	.120	.130	.140	3.05	3.30	3.56
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.055	.060	.065	1.40	1.52	1.65
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

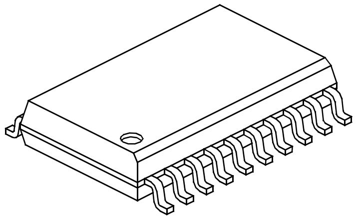
* Controlling Parameter
§ Significant Characteristic

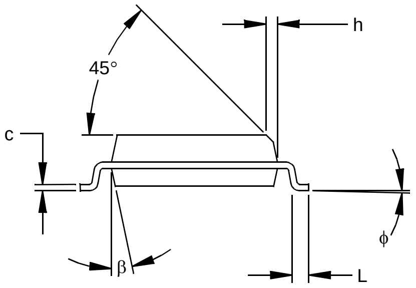
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-019

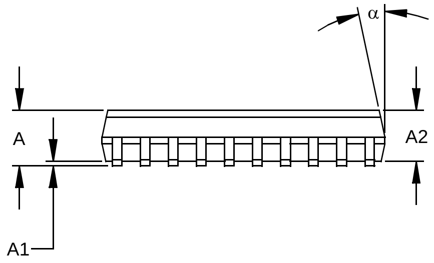
17.7 20-Lead Plastic Small Outline (SO) – Wide, 300 mi (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.496	.504	.512	12.60	12.80	13.00
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-094

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